

## **ATTACHMENT FOR SPECIFICATION AMENDMENTS**

The following is a marked up version of each replacement paragraph and/or section of the specification in which underlines indicates insertions and brackets indicate deletions.

[0001] [TECHNICAL] FIELD OF THE INVENTION

[0003] [BACKGROUND] DESCRIPTION OF THE RELATED ART

[0007] [DISCLOSURE] SUMMARY OF THE INVENTION

[0035] [BEST MODE FOR CARRYING OUT THE INVENTION] DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0127] The microlens array substrate 2 (see Fig. 3) can be fabricated by using this master plate 210 and by applying the processes described above. In this case, the details described above can also be applied here. The entire disclosure of Japanese Patent Application 2000-226675, filed July 27, 2000 is herein incorporated by reference.

## **ATTACHMENT FOR CLAIM AMENDMENTS**

The following is a marked up version of each amended claim in which underlines indicates insertions and brackets indicate deletions.

5. (Amended) The method for fabricating the microlens array according to [any one of claims] claim 1 [to 4], wherein said light transmitting layer precursor includes a substance which can be cured by applying energy.

7. (Amended) The method for fabricating the microlens array according to [any one of claims] claim 1 [to 6], wherein said light transmitting layer precursor is made of a resin.

8. (Amended) A microlens array fabricated by the method according to [any one of claims] claim 1 [to 7].

TO: 09/17/2017